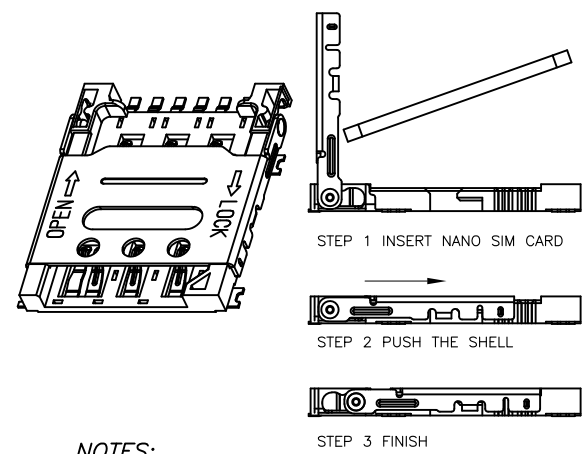
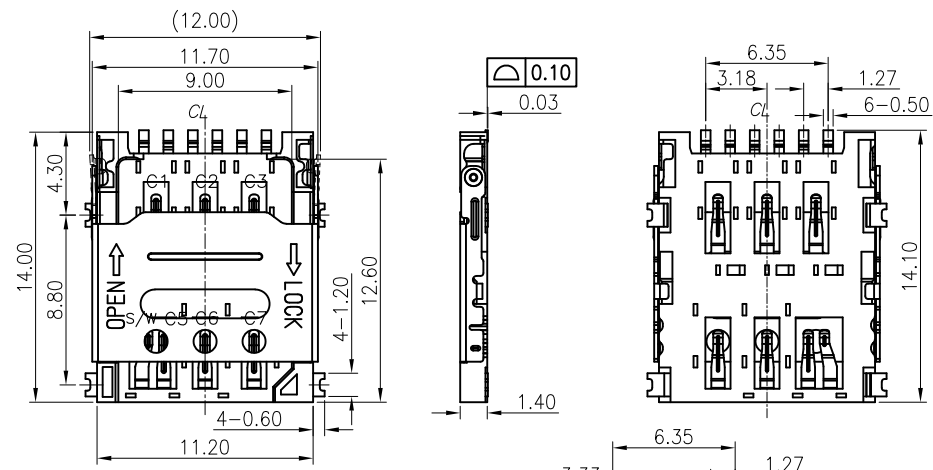
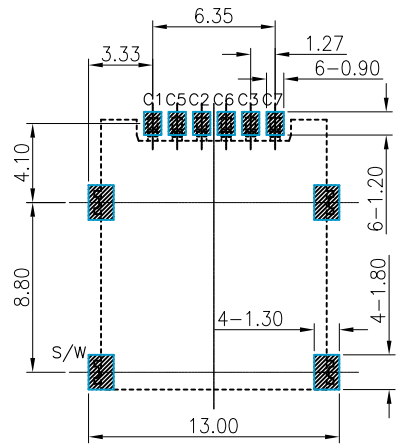
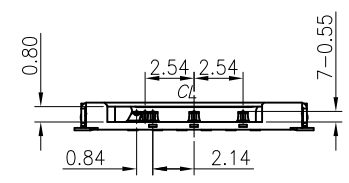


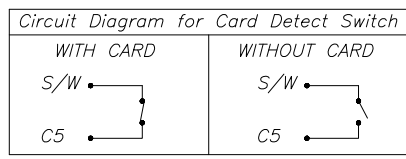
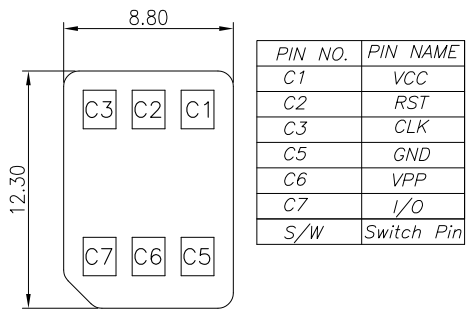
更改 REV	最 终 版 本 MODIFICATION
A	EC09005
B	EC12619



- NOTES:**
- MATERIAL:**
    - Housing: High Temperature Thermoplastic UL94V-0; Color Black.
    - Terminal: Copper Alloy, T=0.12mm.
    - Shell: Stainless Steel, T=0.20mm.
  - FINISH:**
    - Terminal: Plated Gold on the Contact Area and Solder Tails
    - Peg: Plated Gold on the Solder Tails.
  - SPECIALITY:**
    - Rated current: 0.5A
    - Rated voltage: 50V
    - Contact Resistance: 80mΩ MAX
    - Insulation Resistance: 100MΩ MIN 100V DC
    - Dielectric withstanding voltage: 100V AC.
    - Solder ability: 245±5°C, 5±0.5s.
    - Operating condition: Temperature: -40°C~+105°C Humidity: 80% R.H MAX



**RECOMMENDED PCB LAYOUT**  
TOLERANCE ±0.05  
SMT SOLDER AREA



GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司
X±0.50	X*±5°	
.X±0.30	.X*±2°	
.XX±0.20	.XX*±1°	名 称(TITLE) NAND SIM 掀盖 1.4H
单 位(UNIT) mm	料 号(PART NO.) 7SIMC-F0-0023	图 号(DWG NO.) 7SIMC-F0-0023
审 核(APPROVAL)	核 对(CHECKED)	制 图(DRAWN)
SCALE 1:1		张 数 1 / 1
PROJ.		更 改 REV B

